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circumference of the semiconductor chip;

a conductive member extended through the resin wall and retained by the resin wall to electrically conduct the semiconductor chip to the outside; and

a resin lid bonded to the upper end of the resin wall, an inner lead portion of the conductive member being mounted on a base seat part formed as a part of the resin wall, and the semiconductor chip being sealed in the space blocked by the radiating plate, the resin wall and the resin lid.

2. (Amended) A semiconductor device comprising:

a conductive member formed by a lead frame;

a radiating plate formed of a metal plate different from the lead frame;

a semiconductor chip bonded onto the radiating plate;

a resin wall bonded at the lower end to the radiating plate, which retains the conductive member and surrounds the circumference of the semiconductor chip; and

a resin lid bonded to the upper end of the resin wall, the semiconductor chip being sealed in the space blocked by the radiating plate, the resin wall and the resin lid, an inner lead portion of the conductive member being mounted on a base seat part formed as a part of the resin wall, and the conductive member electronically conducting the semiconductor chip to the outside.

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6. (Amended) The semiconductor device according to claim 2, wherein the recessed parts are provided on the opposed side parts of the radiating plate, the protruding parts are protruded and provided on the inner surfaces of the recessed parts, and the lower end part of the resin wall is buried in the recessed parts.